PCN #: 1776
DATE: 11MAY2018
EXPECTED PCN SHIP DATE: 11MAY2018

Quality Assurance
160 Rio Robles
San Jose, CA 95134

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☐ PROCESS CHANGE NOTICE

☒ PRODUCT CHANGE NOTICE

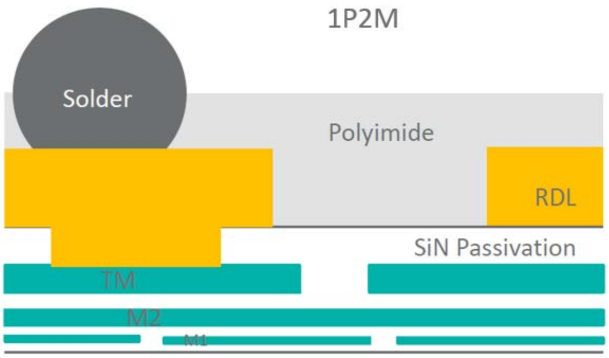
MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

☐ **DESIGN**	☐ **WAFER FAB**	☒ **ASSEMBLY**	☐ **TEST**	☐ **ELEC/MECH SPECS**

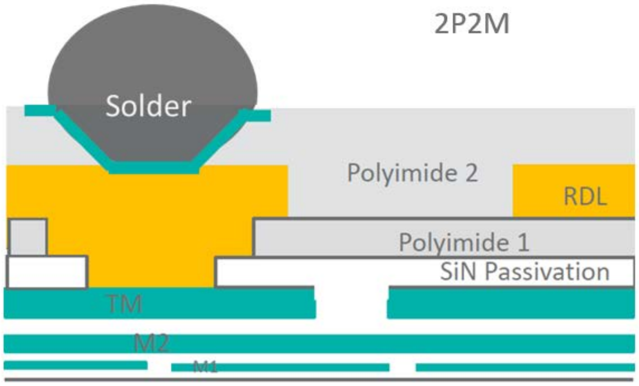
AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN Zip file)

CHANGE FROM: Devices processed with one layer of polyimide and two metal redistributed layers (1P2M) bump flow



CHANGE TO: Devices processed with two layers of polyimide and two metal redistributed layers (2P2M) bump flow



JUSTIFICATION: This change is required to improve the quality and reliability of Maxim’s Flip chip QFN package. Maxim has qualified both UTL (UTAC Thai Limited) and JCAP (JIANGYIN CHANGDIAN ADVANCED PACKAGING CO. LTD, Jiangsu China) to assemble devices with the 2P2M bump process flow. Reference qualification results, report R29667 and R29618. There is no change to the form, fit or function of the devices.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking and the packaging labels or shipment packing slip.

Maxim Integrated’ s Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further Information, please contact either of the people listed below.

Contact your local Maxim Integrated	or	Nasser AliChaouche. PCN Coordinator
Company Representative		408-601-5660 / pcn.coordinator@maximintegrated.com